



RF Power LDMOS Transistor

N-Channel Enhancement-Mode Lateral MOSFET

This 102 W asymmetrical Doherty RF power LDMOS transistor is designed for cellular base station applications covering the frequency range of 720 to 960 MHz.

900 MHz

- Typical Doherty Single-Carrier W-CDMA Performance: $V_{DD} = 48$ Vdc, $I_{DQA} = 750$ mA, $V_{GSB} = 0.8$ Vdc, $P_{out} = 102$ W Avg., Input Signal PAR = 9.9 dB @ 0.01% Probability on CCDF.

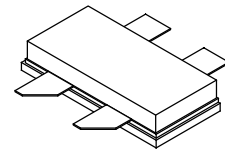
Frequency	G_{ps} (dB)	η_D (%)	Output PAR (dB)	ACPR (dBc)
920 MHz	18.7	53.5	7.2	-29.5
940 MHz	18.9	54.0	7.0	-29.2
960 MHz	18.5	53.4	6.8	-28.8

Features

- Advanced high performance in-package Doherty
- Greater negative gate-source voltage range for improved Class C operation
- Designed for digital predistortion error correction systems

A2V09H400-04S

**720-960 MHz, 102 W AVG., 48 V
 AIRFAST RF POWER LDMOS
 TRANSISTOR**



NI-780S-4L

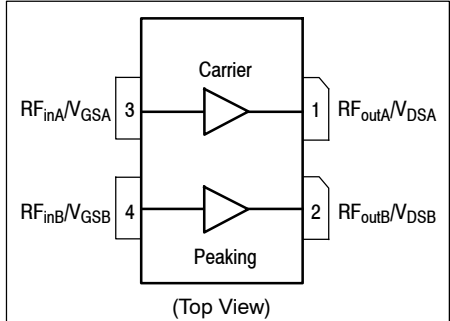


Figure 1. Pin Connections

Table 1. Maximum Ratings

Rating	Symbol	Value	Unit
Drain-Source Voltage	V_{DSS}	-0.5, +105	Vdc
Gate-Source Voltage	V_{GS}	-6.0, +10	Vdc
Operating Voltage	V_{DD}	55, +0	Vdc
Storage Temperature Range	T_{stg}	-65 to +150	°C
Case Operating Temperature Range	T_C	-40 to +150	°C
Operating Junction Temperature Range (1,2)	T_J	-40 to +225	°C

Table 2. Thermal Characteristics

Characteristic	Symbol	Value (2,3)	Unit
Thermal Resistance, Junction to Case Case Temperature 81°C, 107 W Avg., W-CDMA, 48 Vdc, $I_{DQA} = 750$ mA, $V_{GSB} = 0.8$ Vdc, 940 MHz	$R_{\theta JC}$	0.51	°C/W

Table 3. ESD Protection Characteristics

Test Methodology	Class
Human Body Model (per JS-001-2017)	2
Charge Device Model (per JS-002-2014)	C3

Table 4. Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted)

Characteristic	Symbol	Min	Typ	Max	Unit
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Off Characteristics (4)

Zero Gate Voltage Drain Leakage Current ($V_{DS} = 105$ Vdc, $V_{GS} = 0$ Vdc)	I_{DSS}	—	—	10	μAdc
Zero Gate Voltage Drain Leakage Current ($V_{DS} = 55$ Vdc, $V_{GS} = 0$ Vdc)	I_{DSS}	—	—	1	μAdc
Gate-Source Leakage Current ($V_{GS} = 5$ Vdc, $V_{DS} = 0$ Vdc)	I_{GSS}	—	—	1	μAdc

On Characteristics — Side A, Carrier

Gate Threshold Voltage ($V_{DS} = 10$ Vdc, $I_D = 137$ μAdc)	$V_{GS(th)}$	1.3	1.7	2.3	Vdc
Gate Quiescent Voltage ($V_{DD} = 48$ Vdc, $I_D = 750$ mAdc, Measured in Functional Test)	$V_{GSA(Q)}$	2.0	2.4	2.8	Vdc
Drain-Source On-Voltage ($V_{GS} = 10$ Vdc, $I_D = 1.4$ Adc)	$V_{DS(on)}$	0.1	0.2	0.4	Vdc

On Characteristics — Side B, Peaking

Gate Threshold Voltage ($V_{DS} = 10$ Vdc, $I_D = 211$ μAdc)	$V_{GS(th)}$	1.3	1.8	2.3	Vdc
Drain-Source On-Voltage ($V_{GS} = 10$ Vdc, $I_D = 2.1$ Adc)	$V_{DS(on)}$	0.1	0.2	0.5	Vdc

1. Continuous use at maximum temperature will affect MTTF.
2. MTTF calculator available at <http://www.nxp.com>.
3. Refer to AN1955, *Thermal Measurement Methodology of RF Power Amplifiers*. Go to <http://www.nxp.com/RF> and search for AN1955.
4. Each side of device measured separately.

(continued)

Table 4. Electrical Characteristics ($T_A = 25^\circ\text{C}$ unless otherwise noted) (continued)

Characteristic	Symbol	Min	Typ	Max	Unit
Functional Tests ⁽¹⁾ (In NXP Doherty Production Test Fixture, 50 ohm system) $V_{DD} = 48\text{ Vdc}$, $I_{DQA} = 750\text{ mA}$, $V_{GSB} = 0.8\text{ Vdc}$, $P_{out} = 102\text{ W Avg.}$, $f = 920\text{ MHz}$, Single-Carrier W-CDMA, IQ Magnitude Clipping, Input Signal PAR = 9.9 dB @ 0.01% Probability on CCDF. ACPR measured in 3.84 MHz Channel Bandwidth @ $\pm 5\text{ MHz}$ Offset.					
Power Gain	G_{ps}	18.0	18.7	21.0	dB
Drain Efficiency	η_D	48.5	53.5	—	%
P_{out} @ 3 dB Compression Point, CW	P3dB	55.4	56.9	—	dBm
Adjacent Channel Power Ratio	ACPR	—	-29.5	-27.5	dBc

Wideband Ruggedness (In NXP Doherty Production Test Fixture, 50 ohm system) $I_{DQA} = 750\text{ mA}$, $V_{GSB} = 0.8\text{ Vdc}$, $f = 940\text{ MHz}$, Additive White Gaussian Noise (AWGN) with 10 dB PAR

ISBW of 400 MHz at 55 Vdc, 239 W Avg. Modulated Output Power (5 dB Input Overdrive from 107 W Avg. Modulated Output Power)	No Device Degradation
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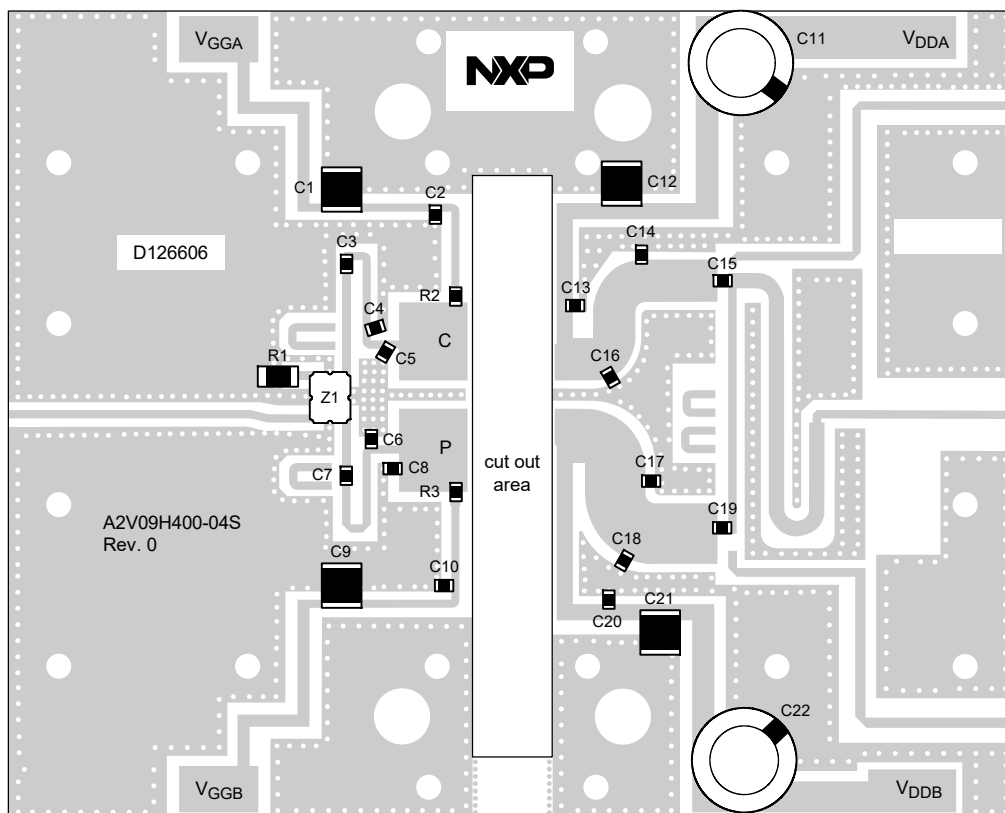
Typical Performance (In NXP Doherty Production Test Fixture, 50 ohm system) $V_{DD} = 48\text{ Vdc}$, $I_{DQA} = 750\text{ mA}$, $V_{GSB} = 0.8\text{ Vdc}$, 920–960 MHz Bandwidth

P_{out} @ 3 dB Compression Point ⁽²⁾	P3dB	—	512	—	W
AM/PM (Maximum value measured at the P3dB compression point across the 920–960 MHz frequency range)	Φ	—	-16	—	°
VBW Resonance Point (IMD Third Order Intermodulation Inflection Point)	VBW_{res}	—	80	—	MHz
Gain Flatness in 40 MHz Bandwidth @ $P_{out} = 102\text{ W Avg.}$	G_F	—	0.6	—	dB
Gain Variation over Temperature (-40°C to +85°C)	ΔG	—	0.031	—	dB/°C
Output Power Variation over Temperature (-40°C to +85°C)	ΔP_{1dB}	—	0.009	—	dB/°C

Table 5. Ordering Information

Device	Tape and Reel Information	Package
A2V09H400-04SR3	R3 Suffix = 250 Units, 32 mm Tape Width, 13-inch Reel	NI-780S-4L

- Part internally input matched.
- $P_{3dB} = P_{avg} + 7.0\text{ dB}$ where P_{avg} is the average output power measured using an unclipped W-CDMA single-carrier input signal where output PAR is compressed to 7.0 dB @ 0.01% probability on CCDF.



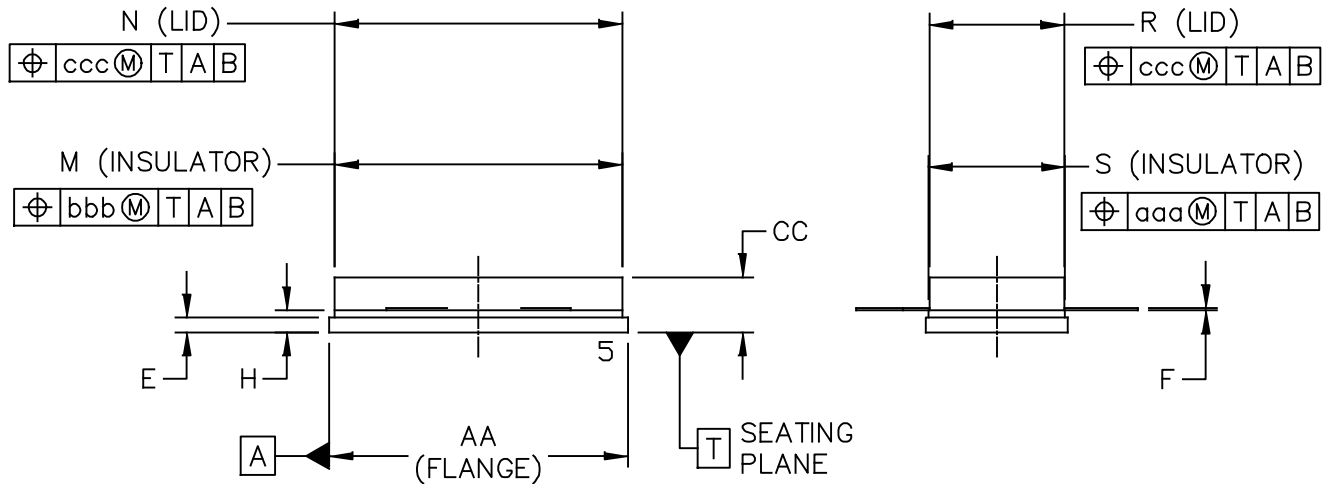
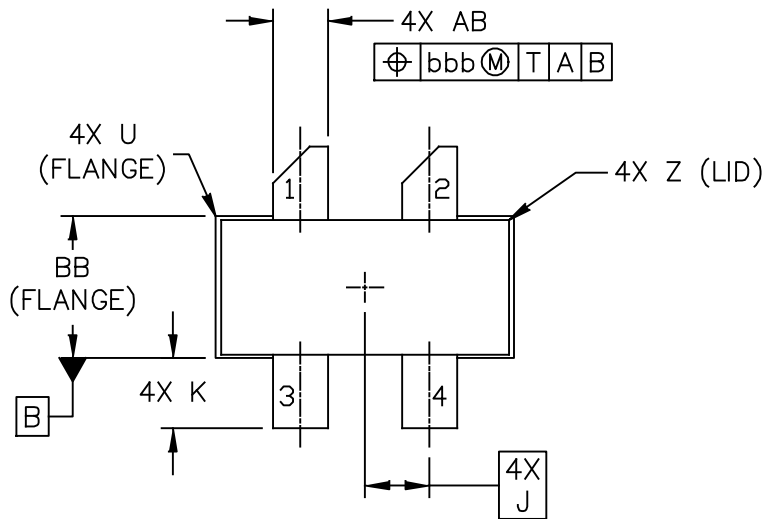
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Figure 2. A2V09H400-04S Test Circuit Component Layout

Table 6. A2V09H400-04S Test Circuit Component Designations and Values

Part	Description	Part Number	Manufacturer
C1, C9, C12, C21	10 μ F Chip Capacitor	C5750X7S2A106M230KB	TDK
C2, C3, C7, C10, C13, C20	47 pF Chip Capacitor	600F470JT250XT	ATC
C4, C8	3.3 pF Chip Capacitor	600F3R3BT250XT	ATC
C5	5.6 pF Chip Capacitor	600F5R6BT250XT	ATC
C6	6.2 pF Chip Capacitor	600F6R2BT250XT	ATC
C11, C22	470 μ F, 100 V Electrolytic Capacitor	MCGPR100V477M16X32	Multicomp
C14	11 pF Chip Capacitor	600F110JT250XT	ATC
C15	10 pF Chip Capacitor	600F100JT250XT	ATC
C16	12 pF Chip Capacitor	600F120JT250XT	ATC
C17	7.5 pF Chip Capacitor	600F7R5JT250XT	ATC
C18	3.9 pF Chip Capacitor	600F3R9BT250XT	ATC
C19	5.1 pF Chip Capacitor	600F5R1BT250XT	ATC
R1	50 Ω , 10 W Termination Chip Resistor	C10A50Z4	Anaren
R2, R3	4.75 Ω , 1/4 W Chip Resistor	CRCW12064R75FKEA	Vishay
Z1	800–1000 MHz, 90°, 2 dB Asymmetric Coupler	CMX09Q02	RN2 Technologies
PCB	Rogers RO4350B, 0.020", $\epsilon_r = 3.66$	D126606	MTL

PACKAGE DIMENSIONS



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	SOT1826-1	01 AUG 2016

NOTES:

1. DIMENSIONING AND TOLERANCING PER ANSI Y14.5M-1994.
2. CONTROLLING DIMENSION: INCH.
3. DELETED
4. DIMENSION H IS MEASURED .030 (0.762) AWAY FROM FLANGE TO CLEAR EPOXY FLOW OUT PARALLEL TO DATUM B.

DIM	INCH		MILLIMETER		DIM	INCH		MILLIMETER	
	MIN	MAX	MIN	MAX		MIN	MAX	MIN	MAX
AA	.805	.815	20.45	20.70	U		.040		1.02
BB	.382	.388	9.70	9.86	Z		.030		0.76
CC	.125	.170	3.18	4.32	AB	.145	.155	3.68	- 3.94
E	.035	.045	0.89	1.14					
F	.003	.006	0.08	0.15	aaa		.005		0.127
H	.057	.067	1.45	1.70	bbb		.010		0.254
J	.175 BSC		4.44 BSC		ccc		.015		0.381
K	.170	.210	4.32	5.33					
M	.774	.786	19.61	20.02					
N	.772	.788	19.61	20.02					
R	.365	.375	9.27	9.53					
S	.365	.375	9.27	9.52					
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					STANDARD: NON-JEDEC				
					SOT1826-1			01 AUG 2016	

PRODUCT DOCUMENTATION, SOFTWARE AND TOOLS

Refer to the following resources to aid your design process.

Application Notes

- AN1908: Solder Reflow Attach Method for High Power RF Devices in Air Cavity Packages
- AN1955: Thermal Measurement Methodology of RF Power Amplifiers

Engineering Bulletins

- EB212: Using Data Sheet Impedances for RF LDMOS Devices

Software

- Electromigration MTTF Calculator
- .s2p File

Development Tools

- Printed Circuit Boards

REVISION HISTORY

The following table summarizes revisions to this document.

Revision	Date	Description
0	Sept. 2019	<ul style="list-style-type: none">• Initial release of data sheet

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